### Fabrication Notes:
1. Use board in high flux design.
2. Layer count is on inner area and 2 on flex area.
3. Handboard thickness 0.001" flex and 0.002" boards.
4. Selective constant polyamide 4546 H & Polyimide.

### Drill Table

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Hit Count</th>
<th>Tool Size</th>
<th>Plated Hole Type</th>
</tr>
</thead>
<tbody>
<tr>
<td>Z</td>
<td>20</td>
<td>10d1/10d2</td>
<td>PTN Round</td>
</tr>
<tr>
<td>J</td>
<td>12</td>
<td>8d1/8d2</td>
<td>PTN Round</td>
</tr>
</tbody>
</table>

### Design Information
- Board Side: 7200 x 1900 mm
- Number of Layers: 4
- MIN TRACK WIDTH: 0.05 mm
- MIN CLEARANCE: 0.03 mm
- MIN PAD SIZE: 0.05 mm
- MINIMUM ALLOWABLE RADIUS: 0.03 mm

### MATERIAL
- TOP: FR-4 High Gp
- OTHER: Polyimide

### THICKNESS
- 62 µm (0.0024"")
- 105 µm (0.0041"")
- 163 µm (0.0064"")

### TOLERANCE
- ± 0.004 mm (±0.00015"")
- ± 0.006 mm (±0.00024"")
- ± 0.010 mm (±0.00039"")

### BOARD FABRIC
-表面 SOLDER MASK
- SOLDER RESIST COLOR: WHITE
- SURFACE ENAMEL: INVERTED GOLD (ENK)
- ARRIVAL PANEL: OUT AND TRIM PER VEND LAYER
- MOLD INJECTION: YES
- SHIPMENT: ELECTRICAL TEST: NONE X REWORK PER ORDER
- MANUFACTURERS: 6/17/00
- SCALE: 1.00

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**Texas Instruments**

Capacitive-based liquid level sensing sensor

**Project:**

Capacitive-based liquid level sensing sensor

**Release:**

Public Release

**File Name:** TIDM_00317.PcbDoc

** Owners:**

David Hang

**Drawn:**

David Hang

**Scaled:**

1.00

14.01.2003

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